





YI J I N ELECTRONI CS CO., LTD

产品承认书

Product acknowledgment

Client客户:	
Product产品:	声表面谐振器
Model型号:	R315M 3030mm
Tabulation 制表:	Production
Date日期:	2011-5-1

承認結果	客戶簽名	客戶承認章	日期	備注
CONCLUSION	SIGNATURE	STAMP	DATE	REMARK
合格				
ACCEPT				
不合格				
REJECT				

审核:	
, ,, ,	(请盖公章)

YJ315M SMD-3030mm

This specification shall cover the characteristics of 1-port SAW resonator with R315M used for remote-control security.

2. Electrical Specification

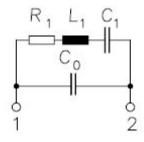
2.1 Maximum Rating

DC Voltage VDC	10V
AC Voltage Vpp	10V 50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
Source Power	0dBm

2.2 Electronic Characteristics

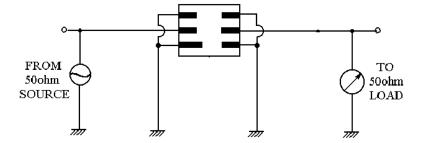
Item		Unites	Minimum	Typical	Maximum	
Center Frequency		MHz	314.925	315.000	315.075	
Insertion Loss		dB		1.4	1.9	
Quality Factor		Unload Q		8000	12800	
		50Ω Loaded Q		1000	2000	
Temperature	Turnover Temperature		$^{\circ}\!\mathbb{C}$	10	25	40
Stability	Freq.temp.Coefficient		ppm/℃		0.032	
Frequency Aging		ppm/yr		<±10		
DC. Insulation Resistance		ΜΩ	1.0			
RF	Motional Resistance R1		Ω		17.6	
Equivalent	Motional Inductance L1		μΗ		118	
RLC Model	Motional Capacitance C1		fF		2.16	
Transducer Static Capacitance C0		pF		2.13		

2.3 Equivalent LC Model

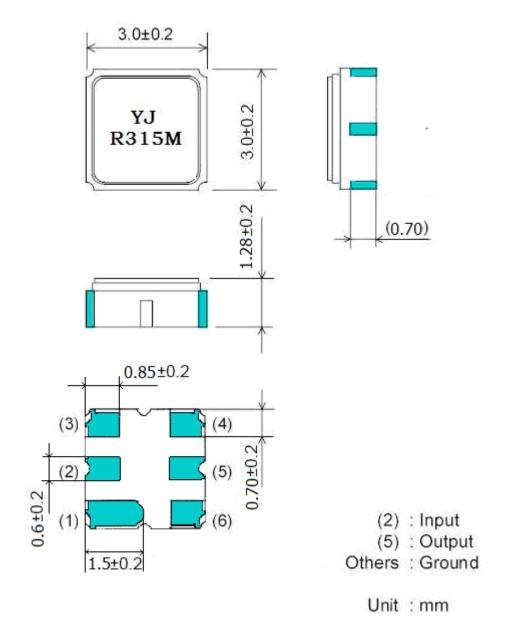


3. Test Circuit

YJ315M SMD-3030mm



4. Dimension



1. KON: Manufacture's logo

2. R315M: Model code

5. Environment Characteristic

5-1 Thermal Shock:

The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40 °C ±3 °C, TB=85 °C ±2 °C, t1=t2=30min, switch time \leq 3min& cycle time : 100 times, recovery time: 2h±0.5h.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

5-3 Solder ability

Submerge the device terminals into the solder bath at 245° C $\pm 5^{\circ}$ C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2

5-4 The Temperature Storage:

- 5.3.1 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C±2°C for 96h±4h, recovery time : 2h±0.5h.
- 5.3.2 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the $-40^{\circ}\text{C} \pm 3^{\circ}\text{C}$ for $96\text{h} \pm 4\text{h}$, recovery time : $2\text{h} \pm 0.5\text{h}$.

5-5 Humidity test:

The components shall remain within the electrical specifications after being kept at the condition of ambient temperature $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$, and $90 \sim 96\%$ RH for $96\text{h} \pm 4\text{h}$.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m for 3 times. The resonator shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 2 hour each in X, Y and Z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The resonator shall fulfill the specifications in 2.2.

6. Remark

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

YJ315M SMD-3030mm

Only leads of component may be soldered. Please avoid soldering another part of component.

7. Packing

7.1 Dimensions

(1) Carrier Tape: Figure 1

(2) Reel: Figure 2

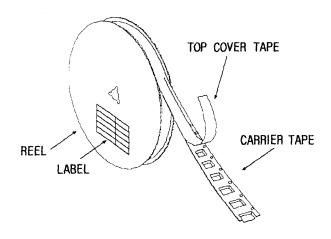
(3) The product shall be packed properly not to be damaged during transportation and storage.

7.2 Reeling Quantity

1000 pcs/reel 7" 3000 pcs/reel 13"

7.3 Taping Structure

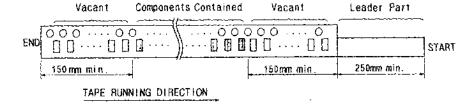
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.

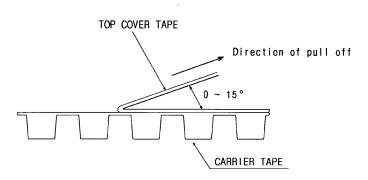


8. Tape Specifications

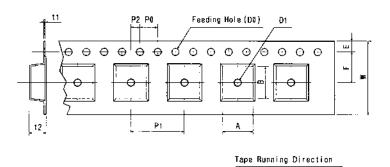
- 8.1 Tensile Strength of Carrier Tape: 4.4N/mm width
- 8.2 Top Cover Tape Adhesion (See the below figure)

(1) pull off angle: 0~15°(2) speed: 300mm/min.

(3) force: 20~70g



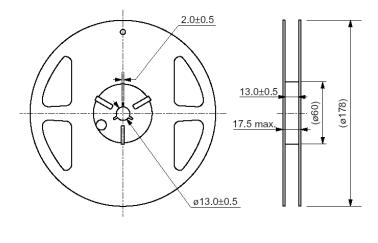
[Figure 1] Carrier Tape Dimensions



[Unit: mm]

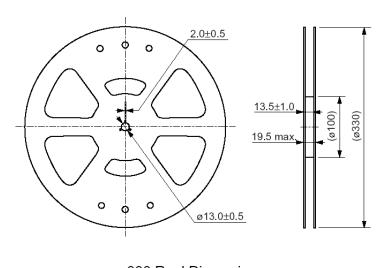
W F E P0 P1 P2 D0D1 t1t2 A В 5.5 1.75 4.0 4.0 Ø1.0 0.3 1.25 $3.3\pm$ $3.3\pm$ 12.0 2.0 Ø1.5 ± 0.25 ± 0.3 ± 0.05 ± 0.1 ± 0.1 ± 0.1 ± 0.05 ± 0.1 ± 0.05 ± 0.1 0.1 0.1

[Figure 2] Reel Dimensions



ø178 Reel Dimension

(in mm)



ø330 Reel Dimension

(in mm)